

Announcement and Call For Papers
The 14th International Symposium on Power
Semiconductor Devices & ICs (ISPSD'02)

Sponsor: IEEE Electron Devices Society
Co-Sponsor: The Institute of Electrical
Engineering of Japan

June 3-7, 2002
Hilton of Santa Fe, Hotel
Santa Fe, New Mexico, USA



ISPSD'02



The 14th International Symposium on Power Semiconductor Devices & ICs (ISPSD'02) provides a forum for technical discussion in all areas of power semiconductor, power IC's, and their hybrid technologies and applications.

Papers can be submitted into the categories of: Low voltage and high voltage, discrete or integrated power semiconductor devices, processes, materials, packaging, and ICs.

Topics of interest include, but are not restricted to the following:

- ◆ **Processes and Materials:** Crystal Growth, Doping Technology, Lifetime Control, Passivation, Characterization, Si, GaAs, SiC, Diamond.
- ◆ **CAD/Simulation:** Device & Circuit Simulation, Layout, Verification Tools.
- ◆ **Devices:** Device Physics, Modeling, Fast Switching Devices, High Power Devices, Intelligent Devices, Pulse Power Devices, Ghz Power Devices, RF-Power Devices, Characterization.
- ◆ **High Voltage and Low Voltage / Power ICs:** Isolation Techniques, SOI, Circuit Design, Device Technology, Monolithic vs Hybrid.
- ◆ **Module and Packaging:** Novel Techniques, Stress & Thermal Simulation, Thermal Management, High Voltage & Power Dissipation.
- ◆ **Application and Switching:** Automotive Electronics, Telecommunication, Display Drive, Power Systems, Power Supply, Motor Control, Battery Management, Evaluation Methods, Power Management, SOA, ESD.

Abstracts Must Clearly State: Purpose of work; How the work is differentiated from prior work; Specific results and their significance with up-to-date reference.

Paper Submission: Prospective authors must submit 50 copies of the abstract consisting of:

- ◆ One page text 500 word summary, headed by: Title, Authors' names, Affiliations, Mailing address, Phone, and FAX number, E-mail address, in English, on 8.5" x 11" size paper.
- ◆ Two pages one side of supporting figures.
- ◆ Mail to Technical Program Chairman: Mr. Dan Kinzer. **Deadline For Submission of the Summary is OCTOBER 15, 2001.** Notice of acceptance will be sent to the authors by December 21, 2001. The final manuscript, in English, will be required for the Proceedings no later than February 15, 2002.

Best Student Paper Award: Papers presented by students and based on their own work will be considered for the Best Student Paper Award **IF THE ABSTRACT IS IDENTIFIED AS A STUDENT PAPER AT THE TIME OF SUBMISSION.** The award presentation will be made at the ISPSD'02.

Further information regarding this symposium, should be directed to the General Chairman, Mr. Taylor R. Efland, or Technical Program Chairman, Mr. Daniel Kinzer.

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Mr. Taylor R. Efland
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Application Form For Hotel Reservation

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Int'l Symposium on Power Semiconductor Devices & ICS

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